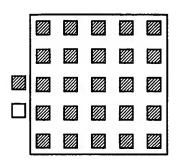


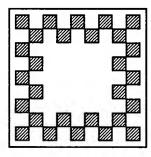
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Prior Art
Figure 1
Perimeter I/O



Prior Art
Figure 2
Staggered Perimeter I/O

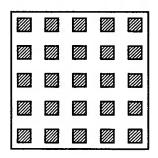


Figure 3
Full Array

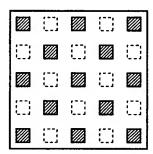


Figure 4
Depopulated Array

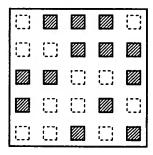
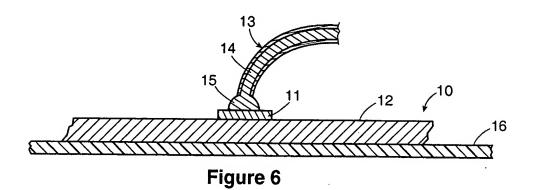


Figure 5
Random Array

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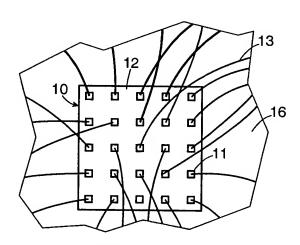


Figure 7

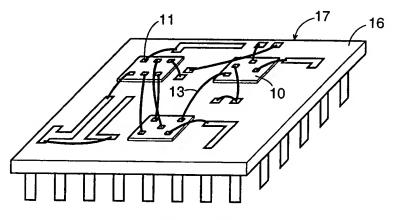


Figure 8

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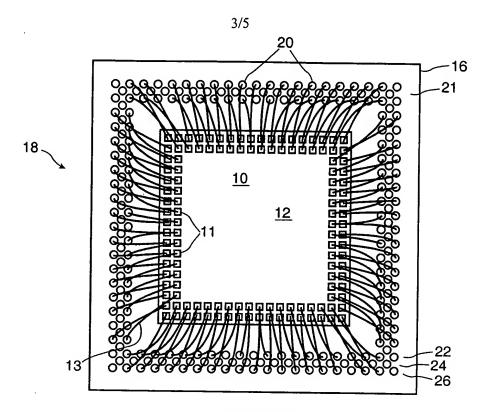


Figure 9

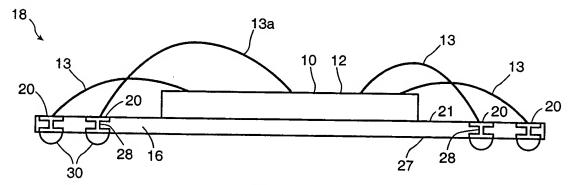


Figure 10

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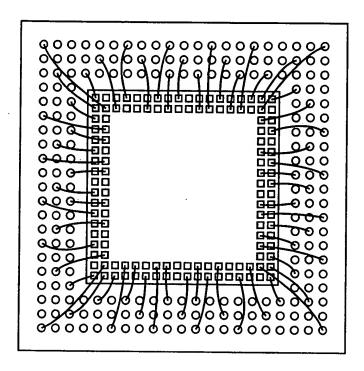


Figure 11b

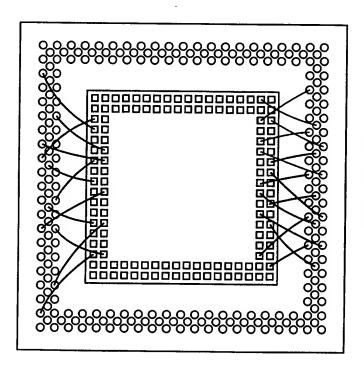


Figure 11

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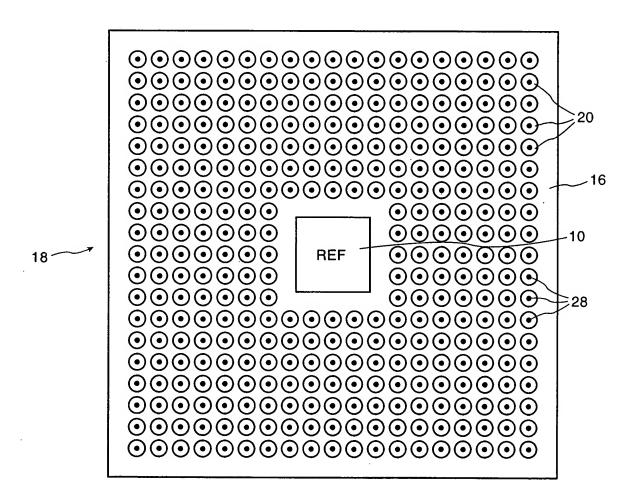


Figure 12